



# 100% Material Declaration Data Sheet FS48

PK150 (v1.2) September 29, 2006

Material Declaration Data Sheet

**Average Weight: 0.1 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.0059</b>	<b>5.90 %</b>
	Silicon	7440-21-3	100.00		0.0059	
<b>Die Attach Material</b>					<b>0.00205</b>	<b>2.05%</b>
	Silver	7440-22-4	75.00	Filler	0.0015375	
	Epoxy Resin	29690-82-2	25.00		0.0005125	
<b>Encapsulant</b>					<b>0.04265</b>	<b>42.65 %</b>
	Epoxy	29690-82-2	26.50		0.01130225	
	Carbon Black	1333-86-4	0.50		0.00021325	
	Silica	60676-86-0	70.00		0.029855	
	Antimony Trioxide	1309-64-4	2.00		0.000853	
	Brominated Flame Retardant (TBBA)	79-94-7	1.00	Flame Retardant	0.0004265	
<b>Laminate</b>					<b>0.03525</b>	<b>35.25 %</b>
	Bismaleimide/Triazine Board	13676-54-5/25722-66-1	69.00		0.0243225	
	Copper	7440-50-8	20.00	Metal Layer	0.00705	
	Nickel	7440-02-0	0.80	Metal Layer	0.000282	
	Gold	7440-57-5	0.20	Metal Layer	0.0000705	
	Resist	Trade Secret	9.00		0.0031725	
	Brominated Flame Retardant (TBBA)	79-94-7	1.00	Flame Retardant	0.0003525	
<b>Bond Wire</b>					<b>0.00095</b>	<b>0.95%</b>
	Gold	7440-57-5	100.00		0.00095	
<b>Solder Balls</b>					<b>0.0132</b>	<b>13.20 %</b>
	Tin	7440-31-5	63.00		0.008316	
	Lead	7439-92-1	37.00		0.004884	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
4/06/06	1.0	Initial release.
7/28/06	1.1	100% Material Declaration.
9/29/06	1.2	Updated component descriptions.